



## Dual N -Channel Enhancement Power MOSFET

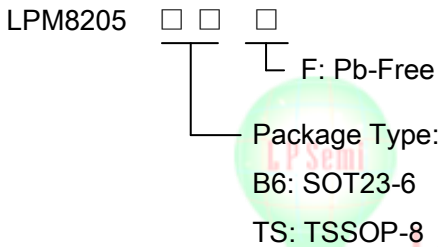
### General Description

The LPM8205 integrates two N-Channel Enhancement MOSFET Transistor. It uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is suitable for using in DC-DC conversion, power switch and charging circuit. Standard Product LPM8205 is Pb-free and Halogen-free.

### Features

- ◆ 100% EAS Guaranteed
- ◆ Green Device Available
- ◆ Super Low Gate Charge
- ◆ Excellent  $CdV/dt$  effect decline
- ◆ Advanced high cell density Trench technology

### Order Information



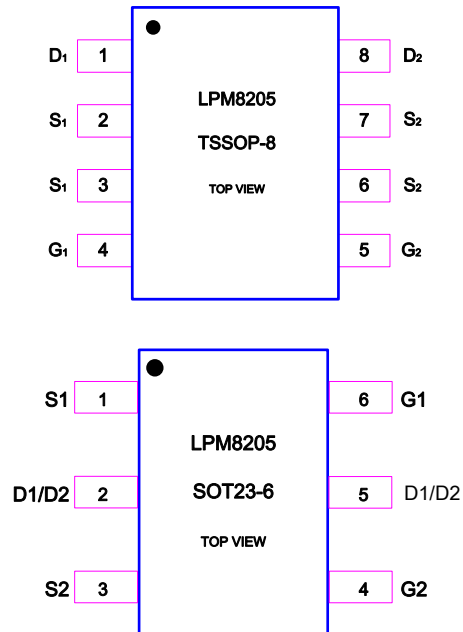
### Applications

- ◇ Driver for Relay, Solenoid, Motor, LED etc.
- ◇ DC-DC converter circuit
- ◇ Power Switch
- ◇ Load Switch
- ◇ Charging

### Marking Information

Device	Marking	Package	Shipping
LPM8205B6F		SOT23-6	
LPM8205TSF		TSSOP-8	

### Pin Configurations



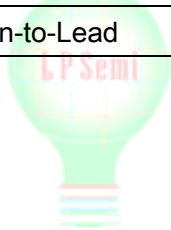


## Absolute Maximum Ratings

Parameter		Symbol	Maximum	Unit
Drain-Source Voltage		$V_{DS}$	20	V
Gate-Source Voltage		$V_{GS}$	$\pm 12$	
Continuous Drain Current	TA=25°C	$I_D$	7.6	A
	TA=70°C		6.1	
Pulsed Drain Current		$I_{DM}$	38	
Power Dissipation	TA=25°C	$P_D$	2	W
	TA=70°C		1.28	
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to 150	°C

## Thermal resistance ratings

Parameter		Symbol	TYP	Unit
Junction-to-Case Thermal Resistance	$t \leq 10s$	$R_{\theta JA}$	48	°C/W
Junction-to-Case Thermal Resistance	Steady State		74	°C/W
Maximum Junction-to-Lead	Steady State	$R_{\theta JL}$	32	°C/W





## Electrical Characteristics

Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	20			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			1 5	μA
I <sub>GSS</sub>	Gate-Body leakage current	V <sub>DS</sub> =0V, V <sub>GS</sub> =12V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.4	0.75	1.1	V
I <sub>D(ON)</sub>	On state drain current	V <sub>GS</sub> =10V, V <sub>DS</sub> =5V	38			A
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =7.6A T <sub>J</sub> =125°C		16.5	23	mΩ
				25	30	
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =7A		18.5	26	
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =6A		24	34	
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =2A		32	52	
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =7.6A		25		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =1A, V <sub>GS</sub> =0V		0.7	1	V
I <sub>S</sub>	Maximum Body-Diode Continuous Current				2.5	A
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz	420	525	630	pF
C <sub>oss</sub>	Output Capacitance		65	95	125	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		45	75	105	pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz	0.8	1.7	2.6	Ω
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub> (10V)	Total Gate Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =7.6A		12.5		nC
Q <sub>g</sub> (4.5V)	Total Gate Charge			6		nC
Q <sub>gs</sub>	Gate Source Charge			1		nC
Q <sub>gd</sub>	Gate Drain Charge			2		nC
t <sub>D(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> =10V, V <sub>DS</sub> =20V, R <sub>L</sub> = 2Ω, R <sub>GEN</sub> =3Ω		3		ns
t <sub>r</sub>	Turn-On Rise Time			7.5		ns
t <sub>D(off)</sub>	Turn-Off DelayTime			20		ns
t <sub>f</sub>	Turn-Off Fall Time			6		ns
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =7.6A, dI/dt=100A/μs		14		ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =7.6A, dI/dt=100A/μs		6		nC



### Typical Characteristics

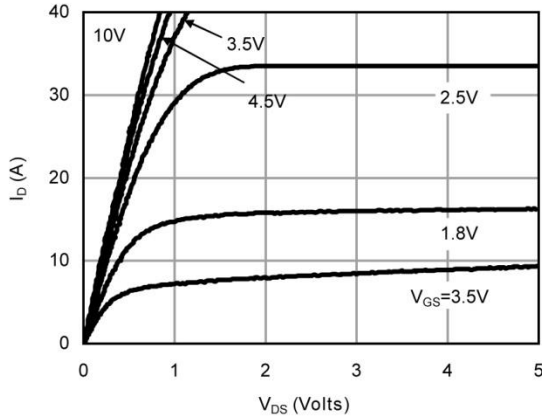


Fig 1: On-Region Characteristics (Note E)

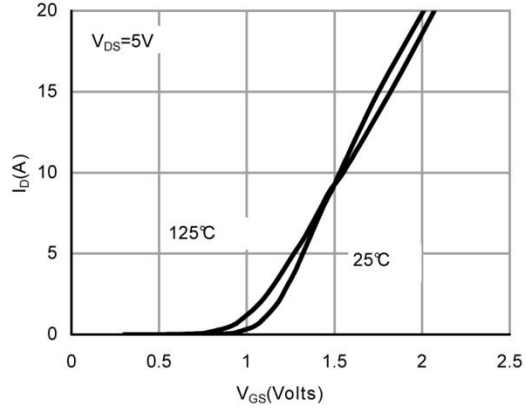


Figure 2: Transfer Characteristics (Note E)

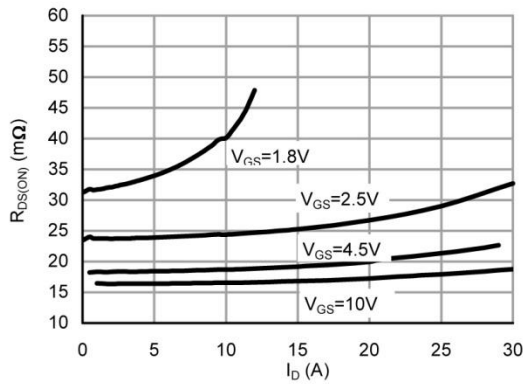


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

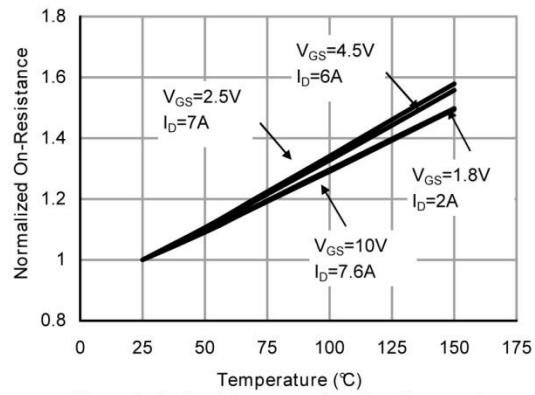


Figure 4: On-Resistance vs. Junction Temperature (Note E)

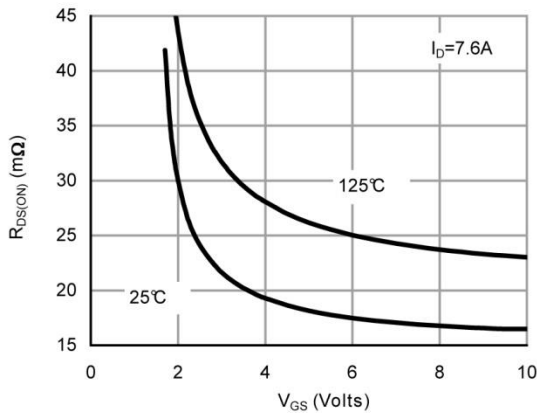


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

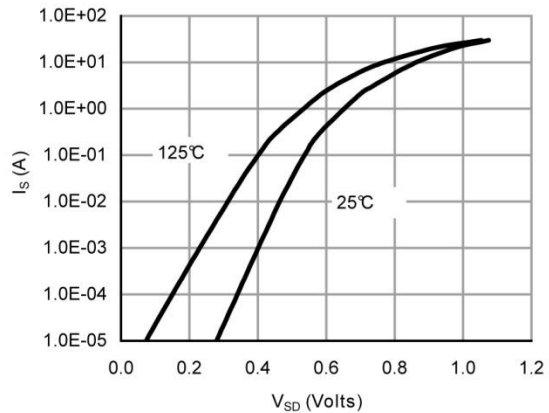


Figure 6: Body-Diode Characteristics (Note E)

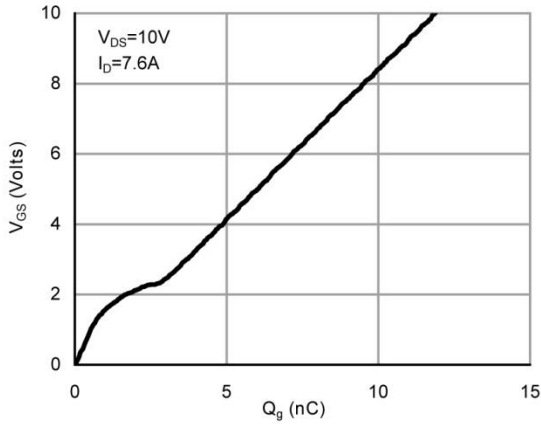


Figure 7: Gate-Charge Characteristics

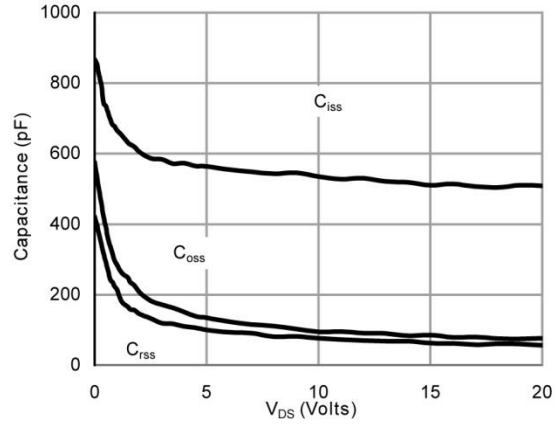


Figure 8: Capacitance Characteristics

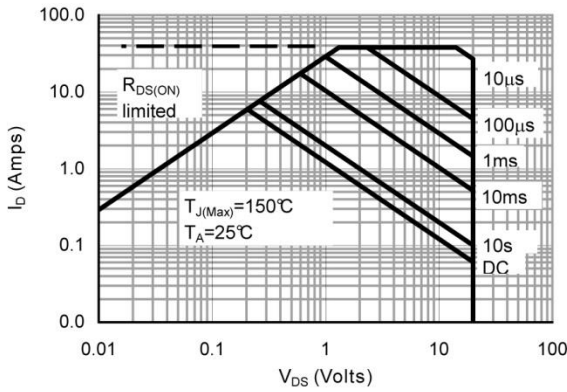


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

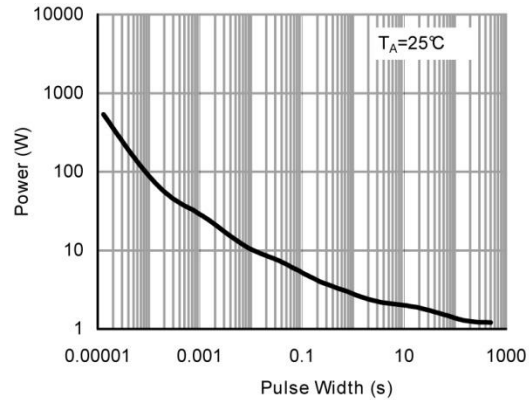


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

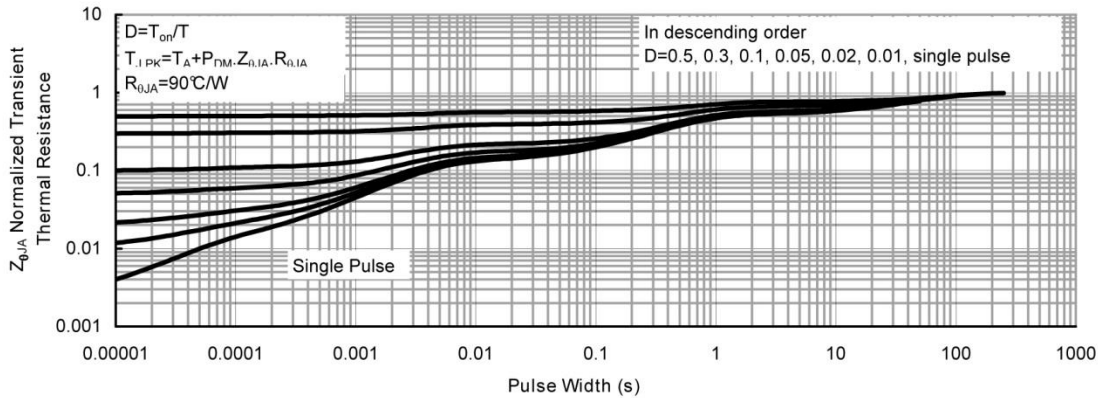
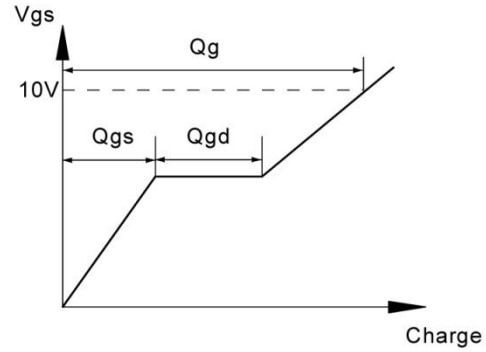
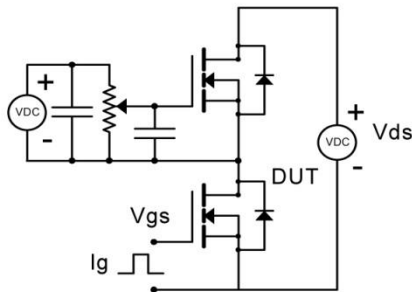


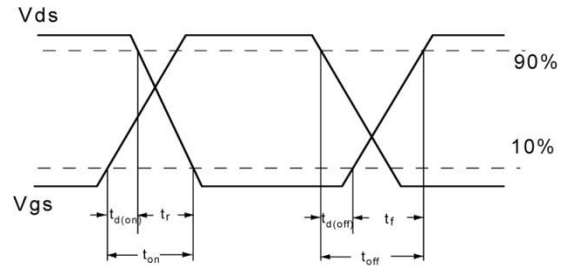
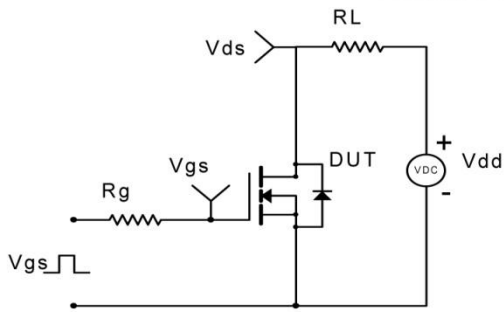
Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)



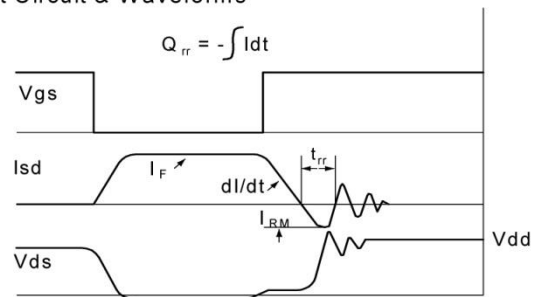
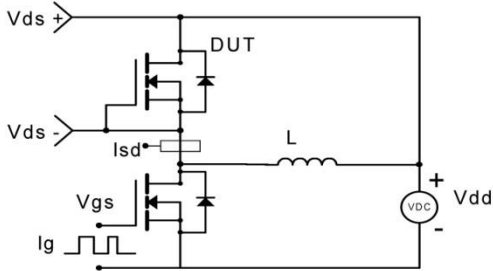
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



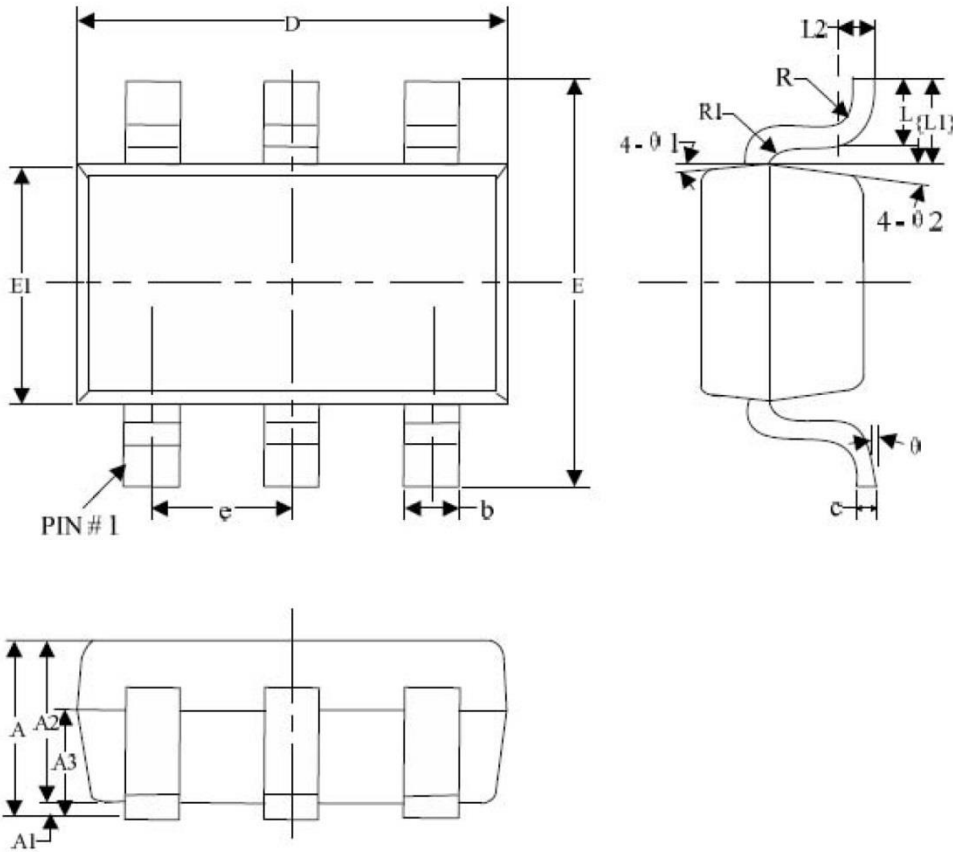
Diode Recovery Test Circuit & Waveforms





Packaging Information

SOT23-6

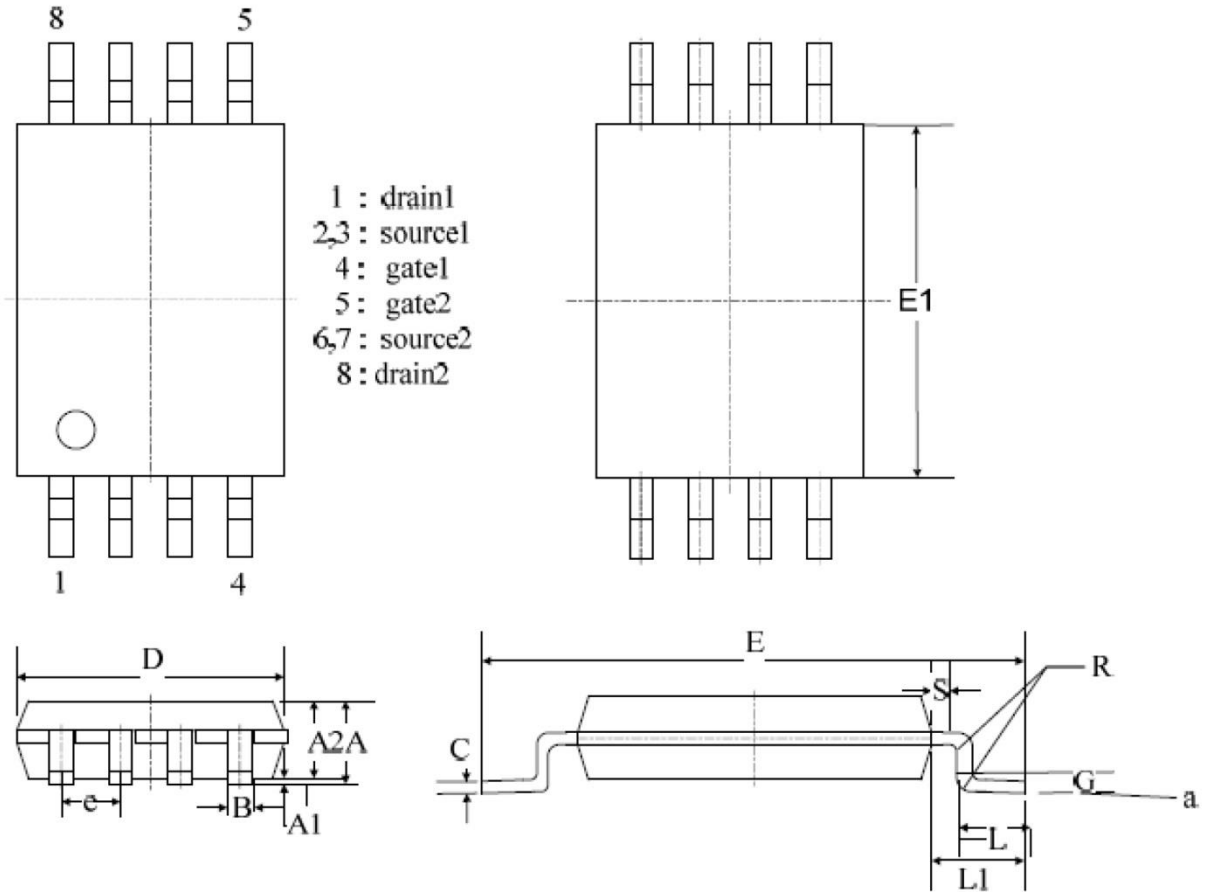


Dimensions (unit: mm)

SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
A	-	-	1.30	e	0.85	0.95	1.05
A1	0	-	0.15	L	0.35	0.45	0.60
A2	0.90	1.10	1.30	L1	0.59REF		
A3	0.60	0.65	0.70	L2	0.25BSC		
b	0.39	-	0.49	R	0.05	-	-
c	0.12	-	0.19	R1	0.05	-	0.02
D	2.85	2.95	3.15	$\theta$	0°	-	8°
E	2.60	2.80	3.00	$\theta_1$	3°	5°	7°
E1	1.55	1.65	1.75	$\theta_2$	6°	8°	10°



TSSOP-8



DIM		A	A(1)	A(2)	B	C	D	E	E1	e	G	L	L1	a	R	S	
MM	Min.	1.05	0.05	0.99	0.19		2.9	6.2	4.3	0.65 BSC	0.254 GAGE PLANE	0.45	0.9	0°	0.09	0.2	
	Nom.	1.1	0.1	1.02	0.25	0.127	3	6.4	4.4			0.6	1	4°			
	Max.	1.2	0.15	1.05	0.3		3.2	6.6	4.5			0.75	1.1	8°			